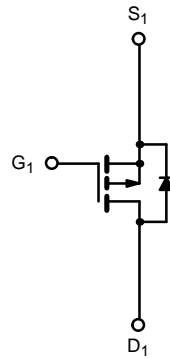
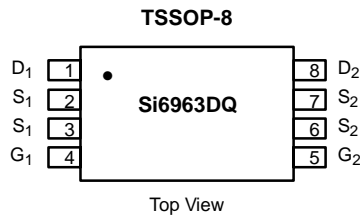




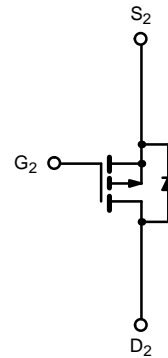
Dual P-Channel 2.5-V (G-S) MOSFET

TrenchFET[®]
Power MOSFETs
2.5-V Rated

PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
-20	0.050 @ $V_{GS} = -4.5$ V	-3.5
	0.085 @ $V_{GS} = -2.5$ V	-2.7



P-Channel MOSFET



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)					
Parameter	Symbol	10 sec	Steady State	Unit	
Drain-Source Voltage	V_{DS}	-20		V	
Gate-Source Voltage	V_{GS}	± 12			
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	$T_A = 25^\circ\text{C}$	-3.5	-3.0	A
		$T_A = 70^\circ\text{C}$	-2.8	-2.5	
Pulsed Drain Current	I_{DM}	-30			
Continuous Source Current (Diode Conduction) ^a	I_S	-1.25	-0.7		
Maximum Power Dissipation ^a	P_D	$T_A = 25^\circ\text{C}$	1.14	0.83	W
		$T_A = 70^\circ\text{C}$	0.73	0.53	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^a	R_{thJA}	$t \leq 10$ sec	86	110	$^\circ\text{C/W}$
		Steady State	124	150	
Maximum Junction-to-Foot (Drain)	R_{thJF}	52	165		

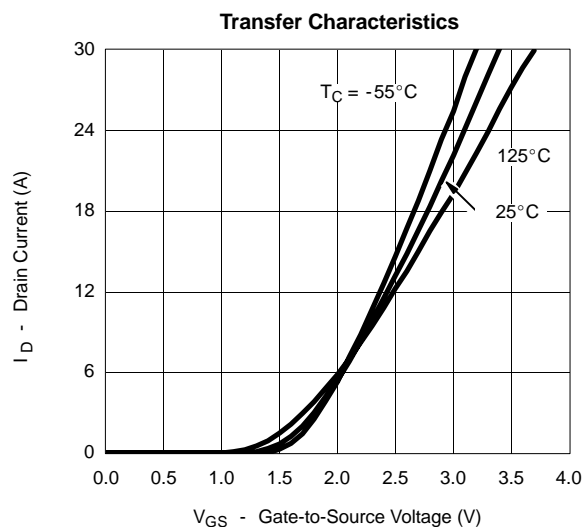
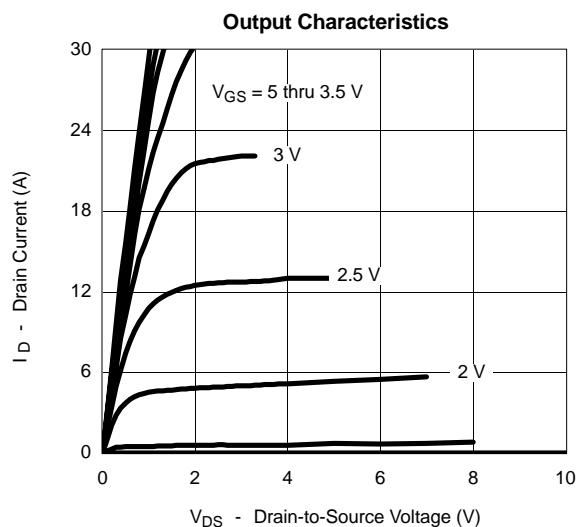
Notes
a. Surface Mounted on FR4 Board.

SPECIFICATIONS (T_J = 25 °C UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-0.6		-1.4	V
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±12 V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V			-1	μA
		V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C			-25	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ -5 V, V _{GS} = -4.5 V	-30			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = -4.5 V, I _D = -3.5 A		0.037	0.050	Ω
		V _{GS} = -2.5 V, I _D = -2.7 A		0.062	0.085	
Forward Transconductance ^a	g _{fs}	V _{DS} = -10 V, I _D = -3.5 A		10		S
Diode Forward Voltage ^a	V _{SD}	I _S = -1.25 A, V _{GS} = 0 V		-0.72	-1.2	V
Dynamic^b						
Total Gate Charge	Q _g	V _{DS} = -10 V, V _{GS} = -4.5 V, I _D = -3.5 A		12.5	20	nC
Gate-Source Charge	Q _{gs}			1.9		
Gate-Drain Charge	Q _{gd}			3.2		
Turn-On Delay Time	t _{d(on)}	V _{DD} = -10 V, R _L = 10 Ω I _D ≅ -1 A, V _{GEN} = -4.5 V, R _G = 6 Ω		20	30	ns
Rise Time	t _r			26	40	
Turn-Off Delay Time	t _{d(off)}			48	75	
Fall Time	t _f			30	45	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = -1.25 A, di/dt = 100 A/μs		30	50	

Notes

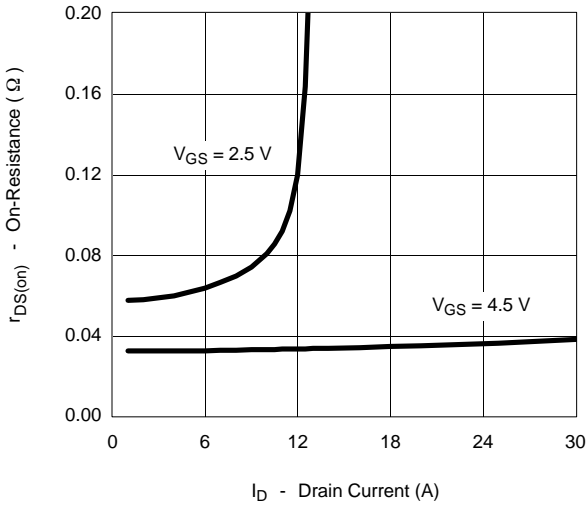
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

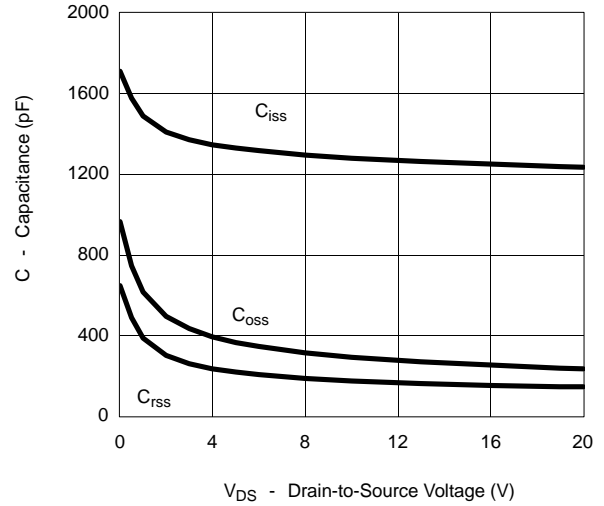


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

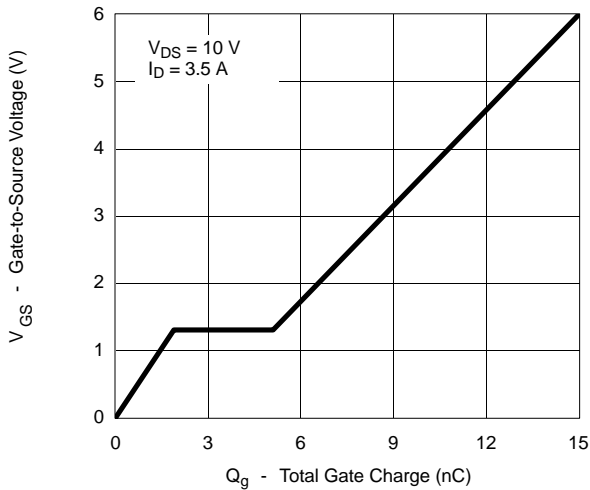
On-Resistance vs. Drain Current



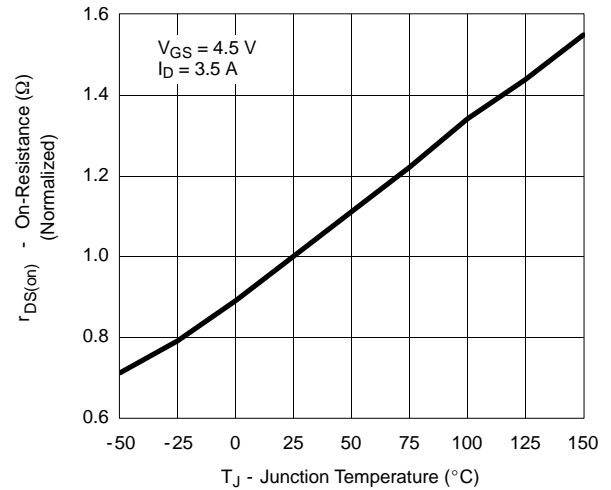
Capacitance



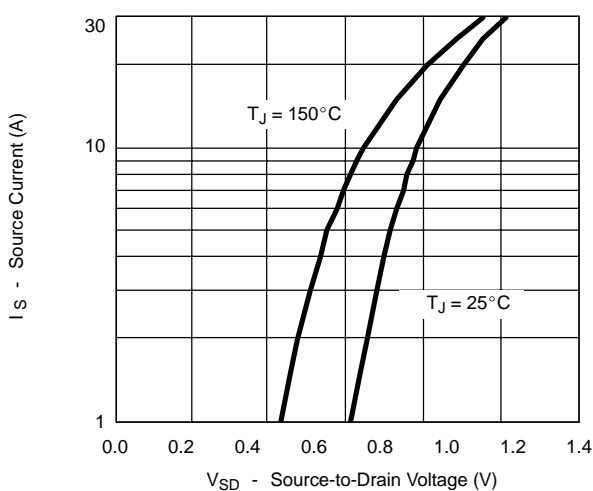
Gate Charge



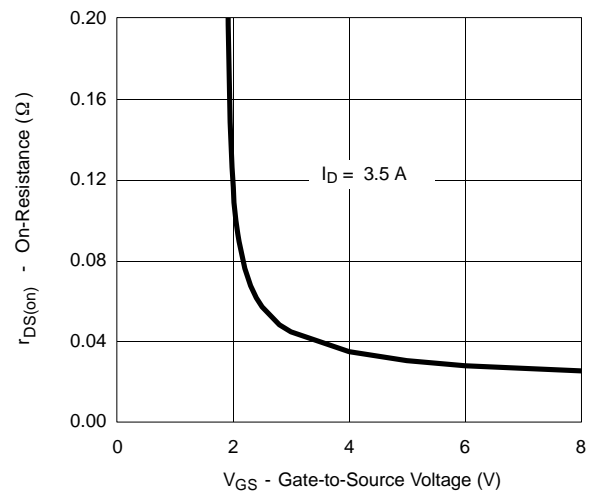
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)

